

BC856ALT1G Series, SBC856ALT1G Series

General Purpose Transistors

PNP Silicon

Features

- AEC-Q101 Qualified and PPAP Capable
- S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Collector-Emitter Voltage BC856, SBC856 BC857, SBC857 BC858, NSVBC858, BC859	V_{CE0}	-65 -45 -30	V
Collector-Base Voltage BC856, SBC856 BC857, SBC857 BC858, NSVBC858, BC859	V_{CBO}	-80 -50 -30	V
Emitter-Base Voltage	V_{EBO}	-5.0	V
Collector Current – Continuous	I_C	-100	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	225 1.8	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	$^\circ\text{C}/\text{W}$
Total Device Dissipation Alumina Substrate, (Note 2) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	300 2.4	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

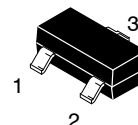
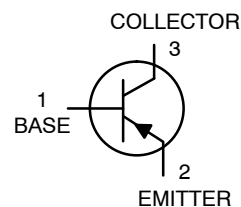
1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.

2. Alumina = $0.4 \times 0.3 \times 0.024$ in 99.5% alumina.



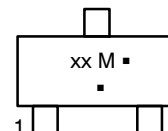
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SOT-23 (TO-236AB)
CASE 318
STYLE 6

MARKING DIAGRAM



xx = Device Code
xx = (Refer to page 6)
M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

BC856ALT1G Series, SBC856ALT1G Series

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector–Emitter Breakdown Voltage (I _C = –10 mA) BC856, SBC856 Series BC857, SBC857 Series BC858, NSVBC858 BC859 Series	V _{(BR)CEO}	–65 –45 –30	– – –	– – –	V
Collector–Emitter Breakdown Voltage (I _C = –10 µA, V _{EB} = 0) BC856 S, SBC856series BC857A, SBC857A, BC857B, SBC857B Only BC858, NSVBC858, BC859 Series	V _{(BR)CES}	–80 –50 –30	– – –	– – –	V
Collector–Base Breakdown Voltage (I _C = –10 µA) BC856, SBC856 Series BC857, SBC857 Series BC858, NSVBC858, BC859 Series	V _{(BR)CBO}	–80 –50 –30	– – –	– – –	V
Emitter–Base Breakdown Voltage (I _E = –1.0 µA) BC856, SBC856 Series BC857, SBC857 Series BC858, NSVBC858, BC859 Series	V _{(BR)EBO}	–5.0 –5.0 –5.0	– – –	– – –	V
Collector Cutoff Current (V _{CB} = –30 V) (V _{CB} = –30 V, T _A = 150°C)	I _{CBO}	– –	– –	–15 –4.0	nA µA

ON CHARACTERISTICS

DC Current Gain (I _C = –10 µA, V _{CE} = –5.0 V) BC856A, SBC856A, BC857A, SBC857A, BC858A BC856B, SBC856B, BC857B, SBC857B, BC858B, NSVBC858B BC857C, SBC857C BC858C (I _C = –2.0 mA, V _{CE} = –5.0 V) BC856A, SBC856A, BC857A, SBC857A, BC858A BC856B, SBC856B, BC857B, SBC857B, BC858B, NSVBC858B, BC859B BC857C, SBC857C, BC858C, BC859C	h _{FE}	– – – 125 220 420	90 150 270 180 290 520	– – – 250 475 800	–
Collector–Emitter Saturation Voltage (I _C = –10 mA, I _B = –0.5 mA) (I _C = –100 mA, I _B = –5.0 mA)	V _{CE(sat)}	– –	– –	–0.3 –0.65	V
Base–Emitter Saturation Voltage (I _C = –10 mA, I _B = –0.5 mA) (I _C = –100 mA, I _B = –5.0 mA)	V _{BE(sat)}	– –	–0.7 –0.9	– –	V
Base–Emitter On Voltage (I _C = –2.0 mA, V _{CE} = –5.0 V) (I _C = –10 mA, V _{CE} = –5.0 V)	V _{BE(on)}	–0.6 –	– –	–0.75 –0.82	V

SMALL–SIGNAL CHARACTERISTICS

Current–Gain – Bandwidth Product (I _C = –10 mA, V _{CE} = –5.0 Vdc, f = 100 MHz)	f _T	100	–	–	MHz
Output Capacitance (V _{CB} = –10 V, f = 1.0 MHz)	C _{ob}	–	–	4.5	pF
Noise Figure (I _C = –0.2 mA, V _{CE} = –5.0 Vdc, R _S = 2.0 kΩ, f = 1.0 kHz, BW = 200 Hz) BC856, SBC856, BC857, SBC857, BC858, NSVBC858 Series BC859 Series	NF	– –	– –	10 4.0	dB

BC856ALT1G Series, SBC856ALT1G Series

BC857/BC858/BC859/SBC857/NSVBC858

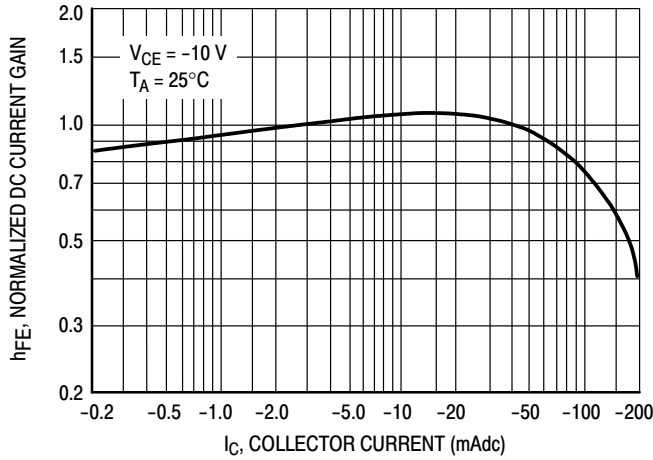


Figure 1. Normalized DC Current Gain

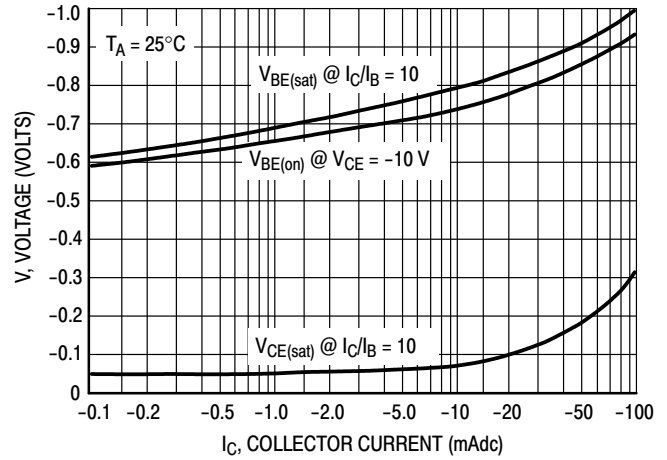


Figure 2. "Saturation" and "On" Voltages

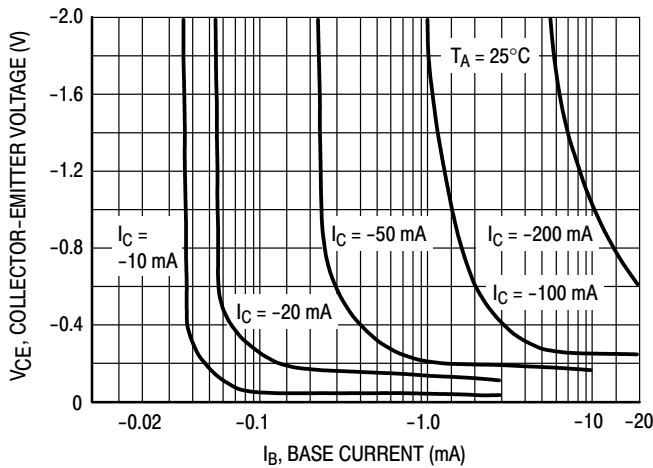


Figure 3. Collector Saturation Region

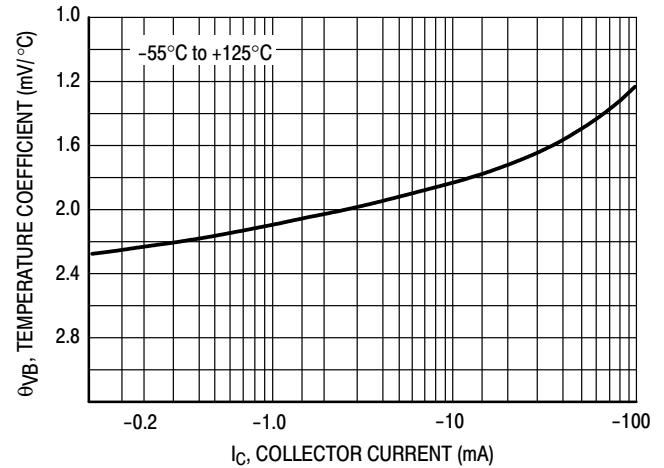


Figure 4. Base-Emitter Temperature Coefficient

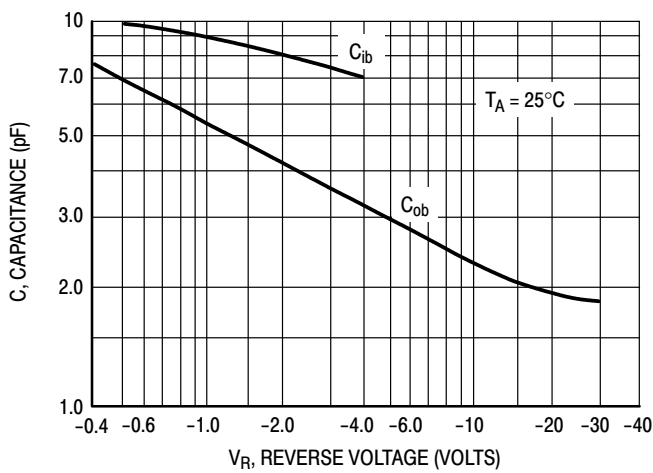


Figure 5. Capacitances

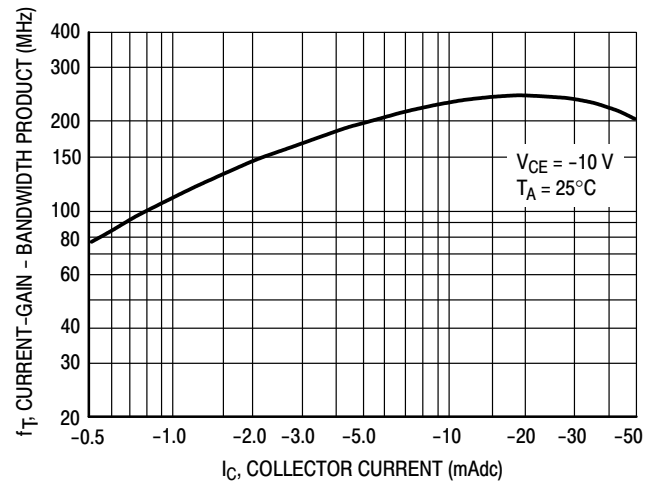


Figure 6. Current-Gain - Bandwidth Product

BC856ALT1G Series, SBC856ALT1G Series

BC856/SBC856

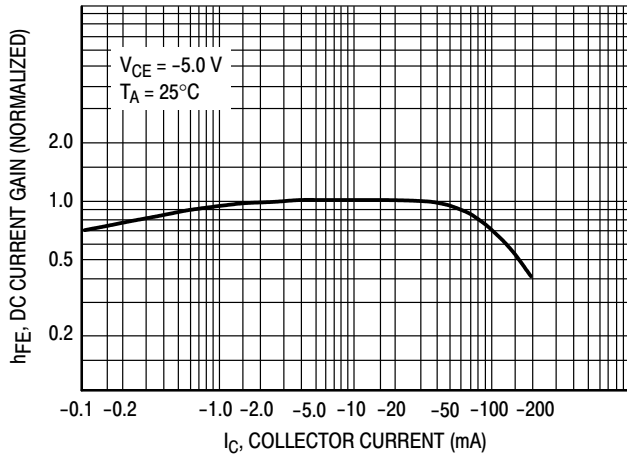


Figure 7. DC Current Gain

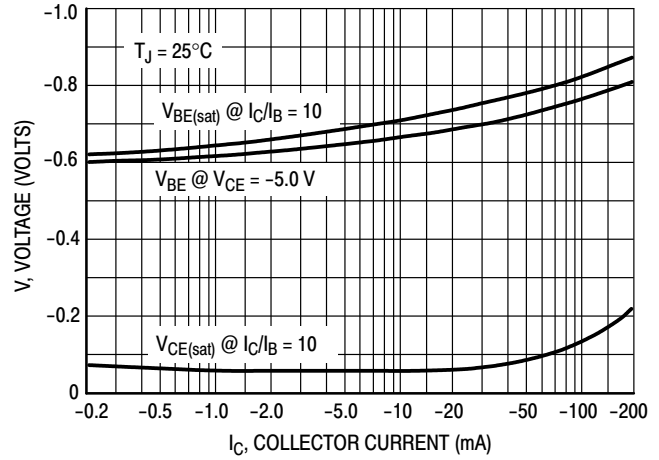


Figure 8. "On" Voltage

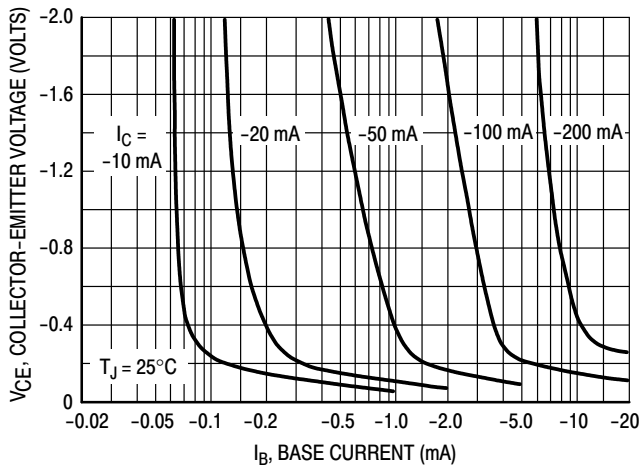


Figure 9. Collector Saturation Region

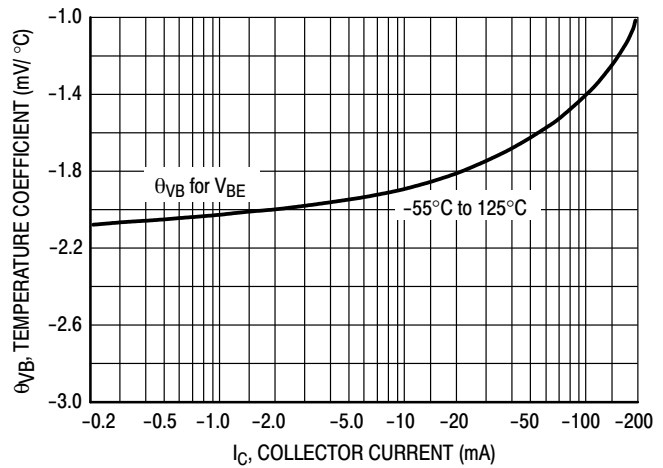


Figure 10. Base-Emitter Temperature Coefficient

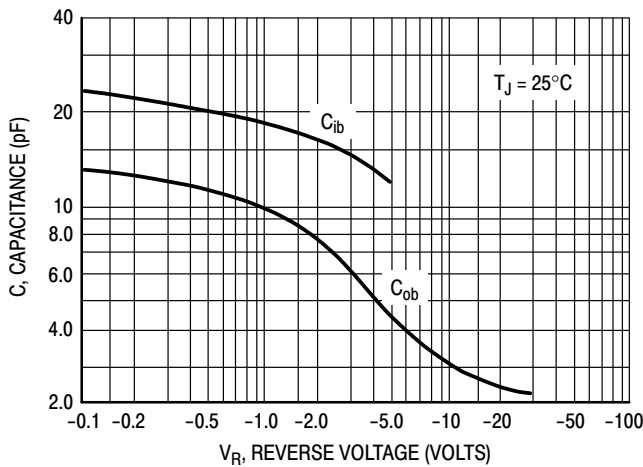


Figure 11. Capacitance

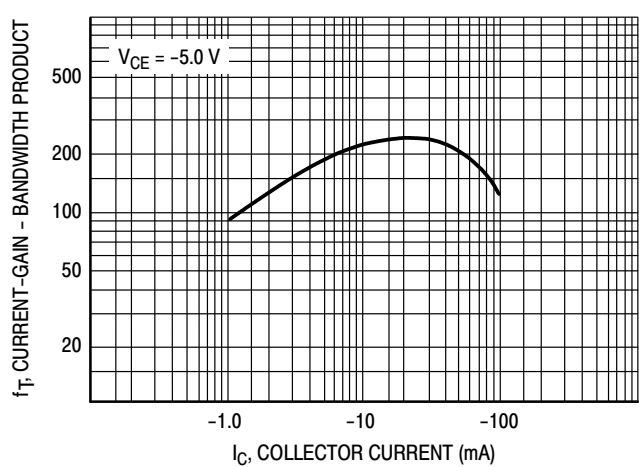


Figure 12. Current-Gain - Bandwidth Product

BC856ALT1G Series, SBC856ALT1G Series

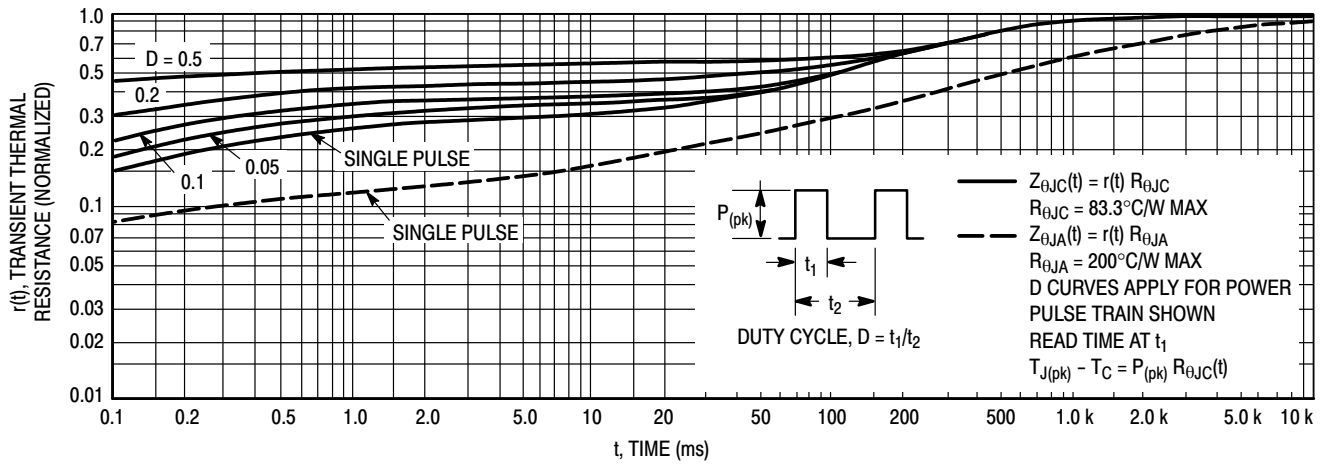


Figure 13. Thermal Response

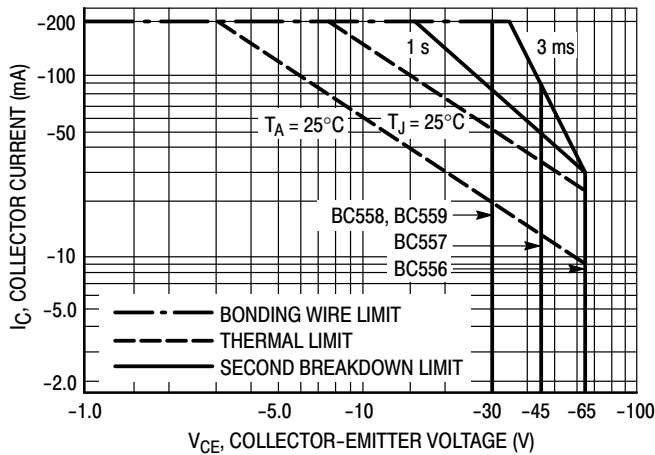


Figure 14. Active Region Safe Operating Area

The safe operating area curves indicate I_C - V_{CE} limits of the transistor that must be observed for reliable operation. Collector load lines for specific circuits must fall below the limits indicated by the applicable curve.

The data of Figure 14 is based upon $T_{J(pk)} = 150^\circ\text{C}$; T_C or T_A is variable depending upon conditions. Pulse curves are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150^\circ\text{C}$. $T_{J(pk)}$ may be calculated from the data in Figure 13. At high case or ambient temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by the secondary breakdown.

BC856ALT1G Series, SBC856ALT1G Series

ORDERING INFORMATION

Device	Marking	Package	Shipping†
BC856ALT1G	3A	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SBC856ALT1G			
BC856ALT3G			10,000 / Tape & Reel
BC856BLT1G	3B	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SBC856BLT1G			
BC856BLT3G			
SBC856BLT3G			10,000 / Tape & Reel
BC857ALT1G	3E	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SBC857ALT1G			
BC857BLT1G	3F	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SBC857BLT1G			
BC857BLT3G			10,000 / Tape & Reel
BC857CLT1G	3G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SBC857CLT1G			
BC857CLT3G			10,000 / Tape & Reel
BC858ALT1G	3J	SOT-23 (Pb-Free)	3,000 / Tape & Reel
BC858BLT1G	3K	SOT-23 (Pb-Free)	
NSVBC858BLT1G			
BC858BLT3G	3L	SOT-23 (Pb-Free)	10,000 / Tape & Reel
BC858CLT1G		SOT-23 (Pb-Free)	3,000 / Tape & Reel
BC858CLT3G		SOT-23 (Pb-Free)	10,000 / Tape & Reel
BC859BLT1G	4B	SOT-23 (Pb-Free)	3,000 / Tape & Reel
BC859BLT3G		SOT-23 (Pb-Free)	10,000 / Tape & Reel
BC859CLT1G	4C	SOT-23 (Pb-Free)	3,000 / Tape & Reel
BC859CLT3G		SOT-23 (Pb-Free)	10,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

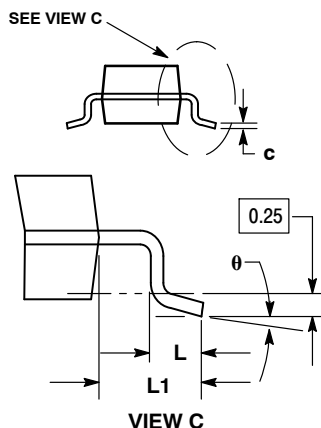
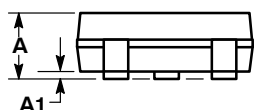
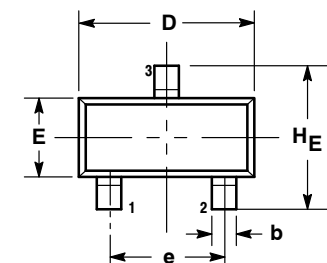
BC856ALT1G Series, SBC856ALT1G Series

PACKAGE DIMENSIONS

SOT-23 (TO-236)

CASE 318-08

ISSUE AP



NOTES:

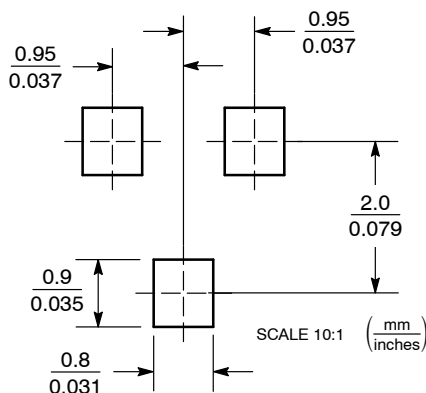
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°	---	10°	0°	---	10°

STYLE 6:

- PIN 1. BASE
2. EMITTER
3. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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